

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration
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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class* Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information			
Company Name *	Company Unique ID	Unique ID Authority	Response Date*
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Aug 09, 2014 01:50 AM
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Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item	Mfr Item Number		Mfr Item Name		Version		Manufacturing Site	Weight*	UOM	Unit Type
2N3904TFR	2N390)4TFR	TO-92-3 (FeLFAuBW)Auk-D				SUBCONTRACTOR		0.223091	g	Each
Manufacturing Process Information											
Terminal Finish	Base Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Temperature		No Reflow cycles			
Matte Tin (Sn)	CU Alloy	Not	ot Applicable		С		seconds		Not Applicable		

^{*} Required Field

RoHS Material Composition Declaration

Declaration Type * Custom

RoHS Directive 2011/65/EU **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance * Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

Declaration Signature

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name TO-92-3 (FeLFAuBW)Auk-D

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.075	Supplier		Silicon	0.075	7440-21-3	336
Encapsulation	Thermoplastics	112.000	В	Antimony/Antimony Compounds	Antimony Trioxide	2.800	1309-64-4	12551
			В	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	3.360	6386-73-8	15061
			Supplier		Carbon Black	0.840	1333-86-4	3765
			Supplier		Epoxy Resin	22.400	29690-82-2	100407
			Supplier		Silica, vitreous	82.600	60676-86-0	370252
Lead Frame	Other Ferrous alloys, non-stainless steels	101.001	Supplier		Copper	0.904	7440-50-8	4052
			Supplier		Iron	98.400	7439-89-6	441075
			Supplier		Manganese	0.505	7439-96-5	2264
			В	Nickel (external applications only)	Nickel	0.182	7440-02-0	816
			Supplier		Silver	1.010	7440-22-4	4527
Plating	Other Nonferrous metals & alloys	9.940	Supplier		Tin	9.940	7440-31-5	44556
Wire Bond	Precious metals	0.076	Supplier		Gold	0.076	7440-57-5	341